## IN THE CLAIMS

1-8 (Canceled)

9. (Original) A semiconductor die stencil having a top surface, a bottom surface, and one or more side surfaces, the bottom surface having a surface tension less than a surface tension of the top surface and less than a surface tension of the side surfaces.

10. (Original) A semiconductor die stencil having at least a first surface and a second surface, the first surface having a surface tension less than a surface tension of the second surface to retard adhesive running from the second surface onto the first surface.

11. (Original) The semiconductor die stencil of claim 10, wherein the first surface is a bottom surface.

12. (Original) The semiconductor die stencil of claim 10, wherein the second surface is a top surface.

13. (Original) The semiconductor die stencil of claim 10, wherein the second surface is a side surface.

14. (Original) A semiconductor die stencil having at least a first surface and a second surface, the first surface having a surface tension greater than a surface tension of the second surface to promote adhesive running onto a semiconductor die

15-39 (Canceled)

40. (New) The semiconductor die stencil of claim 9 wherein the top surface is a coating selected from the group consisting of any one or more of tungsten, tungsten carbide, tungsten nitride, nickel, and nickel alloy in any combination

41. (New) The semiconductor die stencil of claim 9 wherein the bottom surface is a polymeric material..

42. (New) The semiconductor die stencil of claim 12 wherein the top surface is a coating selected from the group consisting of any one or more of tungsten, tungsten carbide, tungsten nitride, nickel, and nickel alloy in any combination

43. (New) The semiconductor die stencil of claim 11 wherein the bottom surface is a polymeric material.

44 (New) The semiconductor die stencil of claim 14 wherein the second surface is a polymeric material.

45. (New) The semiconductor die stencil of claim 14 wherein the first surface is a coating selected from the group consisting of any one or more of tungsten, tungsten carbide, tungsten nitride, nickel, and nickel alloy in any combination.

46. (New) A semiconductor die stencil to assist in application of a printable adhesive in a desired pattern onto a semiconductor die comprising:

a stainless steel sheet which is impervious to a printable adhesive applied thereto;

a plurality of apertures in the sheet of material defining a desired pattern for application of the printable adhesive; and

a coating applied to at least one top or one bottom surface of the sheet to retard spreading of the printable adhesive onto the at least one top or one bottom surface of the sheet without obstruction of the flow of printable adhesive through the apertures.

47. (New) The semiconductor die stencil of claim 46, wherein both the coating and the material have a surface tension, the surface tension of the coating being less than the surface tension of the material.

48. (New) The semiconductor die stencil of claim 47, wherein the surface tension of the coating is at least an order of magnitude less than the surface tension of the material.

49. (New) The semiconductor die stencil of claim 48, wherein the coating is a polymeric material.

50. (New) A semiconductor die stencil to assist in application of a printable adhesive material onto a substrate comprising:

a sheet of material which is impervious to a printable adhesive material applied thereto;

a plurality of apertures in the sheet material defining a desired pattern; and

a coating applied to at least one surface of the sheet to promote spreading of the printable adhesive material.

51. (New) The semiconductor die stencil of claim 50, wherein both the coating and the sheet have a surface tension, the surface tension of the coating greater than the surface tension of the sheet.

52. (New) The semiconductor die stencil of claim 50, wherein the coating is selected from the group consisting of tungsten, tungsten carbide, tungsten nitride, nickel, and nickel alloy.